

Co-packaged low-loss photonics in-stock vs copper cable



Overview

Copper remains a local-reach technology, optimized for in-package communication, while optics take over at package-to-package, board-level, and rack-scale distances. One industry example is Ayar Labs' UCle optical interconnect chiplet TeraPHY, delivering 8 Tbps of. Co-packaged optics (CPO) is a disruptive approach to increasing the interconnecting bandwidth density and energy efficiency by dramatically shortening the electrical link length through advanced packaging and co-optimization of electronics and photonics. CPO is widely regarded as a promising. Imagine buying a Ferrari capable of 200 MPH, only to drive it exclusively in rush-hour gridlock. That's the problem facing the semiconductor industry today. We have built processors—like NVIDIA's Blackwell—that were unimaginable ten years ago, but we're choking them with copper wires that haven't. The silicon photonics industry is entering a period of rapid growth and diversification, according to Yole Group 's new report, Silicon Photonics 2025 – Focus on SOI, SiN, LNOI & InP Platforms. As AI continues to drive exponential demand for bandwidth, the sector is transitioning to higher data. As AI clusters push beyond 100 Tb/s per node, the gap between what silicon can generate and what traditional copper interconnects can deliver is widening fast. Three hurdles are now colliding: First, power delivery is nearing practical limits. Adding GPUs no longer scales linearly, with power and. Co-packaged optics (CPO) technology offers a promising solution by integrating photonic integrated circuits (PICs) directly within or close to electronic integrated circuit (EIC) packages.

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